

0288290100
32199
10/07/01

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10063870	FILING DATE 05/21/2002	CLASS 228	SUBCLASS 102	GAU 1725	EXAMINER TRAN
**APPLICANTS: Araki Chihiro;					
**CONTINUING DATA VERIFIED: <i>none</i>					
BEST AVAILABLE COPY					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 2001-161742 05/30/2001					
PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>			
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiners's initials			ATTORNEY DOCKET NO SIMTEK6353		
TITLE : Wire bonding method and apparatus therefor					
U.S. DEPT. OF COMM./PAT. & TM-PTO-436L(Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED		
			Total Claims		Print Claim for O.G
ISSUE FEE		Primary Examiner	DRAWING		
Amount Due	Date Paid		Sheets Drwg.	Figs.Drwg.	Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner			
WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368. Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.					

FILED WITH:

DISK (CRF)

CD-ROM
(Attached in pocket on right inside flap)